



富满微电子集团股份有限公司

FINE MADE MICROELECTRONICS GROUP CO., LTD.

055N85 (文件编号: S&CIC2013)

N-Channel Trench Power MOSFET

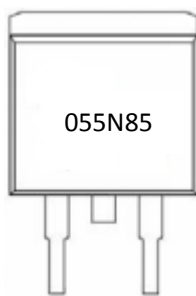
Features

- $V_{DS}=85V$; $I_D=110A@V_{GS}=10V$; $R_{DS(ON)}<6.8m\Omega @V_{GS}=10V$
- Special Designed for E-Bike Controller Application
- Ultra Low On-Resistance
- High UIS and UIS 100% Test

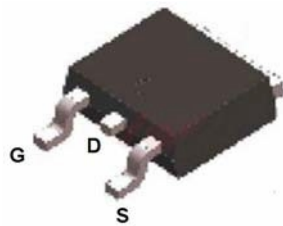
Application

- 64V E-Bike Controller Applications
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply

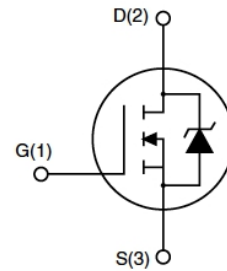
Package



Marking and pin assignment



TO-263 top view



Schematic diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
055N85	055N85	TO-263	-	-	-

Table 1. Absolute Maximum Ratings ($T_A=25^\circ C$)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	85	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0V$)	± 20	V
$I_{D(DC)}$	Drain Current (DC) at $T_c=25^\circ C$	110	A
$I_{D(DC)}$	Drain Current (DC) at $T_c=100^\circ C$	78	A
$I_{DM (pluse)}$	Drain Current-Continuous@ Current-Pulsed (Note 1)	420	A
dv/dt	Peak Diode Recovery Voltage	7.2	V/ns
P_D	Maximum Power Dissipation ($T_c=25^\circ C$)	202	W
	Derating Factor	1.46	W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy (Note 2)	528	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ C$

Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature

2. E_{AS} condition: $T_J=25^\circ C, V_{DD}=40V, V_G=10V, R_G=25\Omega, L=0.5mH$



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Table 2. Thermal Characteristic

Symbol	Parameter	Value	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	---	0.8	$^{\circ}\text{C}/\text{W}$

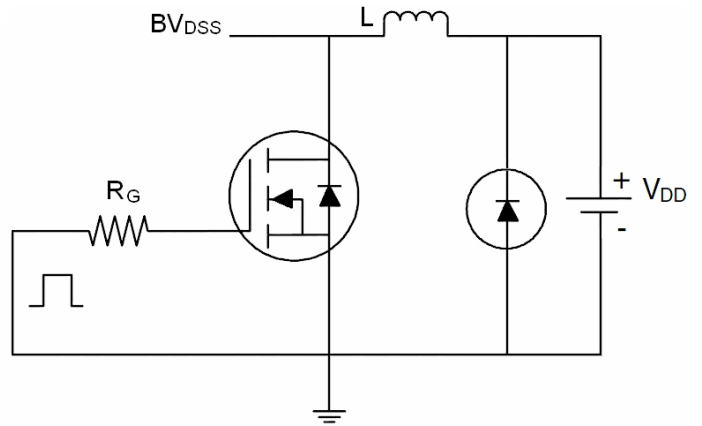
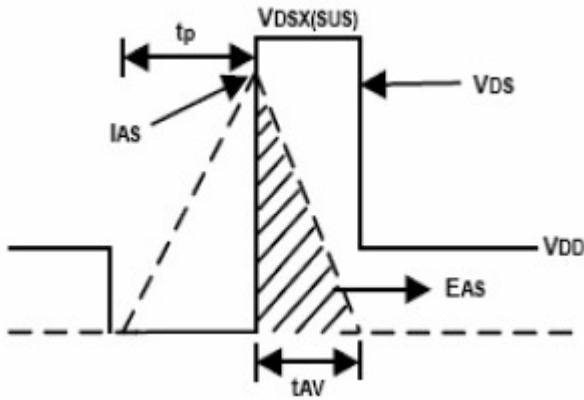
Table 3. Electrical Characteristics (TA=25 $^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	85			V
I_{DSS}	Zero Gate Voltage Drain Current($T_c=25^{\circ}\text{C}$)	$V_{DS}=85\text{V}, V_{GS}=0\text{V}$			1	μA
I_{GSS}	Gate-Body Leakage Current	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	2		4	V
$R_{DS(on)}$	Drain-Source On-State Resistance	$V_{GS}=10\text{V}, I_D=40\text{A}$		5.5	6.8	m Ω
Dynamic Characteristics						
g_{FS}	Forward Transconductance	$V_{DS}=10\text{V}, I_D=15\text{A}$	25			S
C_{iss}	Input Capacitance	$V_{DS}=25\text{V}, V_{GS}=0\text{V},$ $f=1.0\text{MHz}$		5560		PF
C_{oss}	Output Capacitance			482		PF
C_{rss}	Reverse Transfer Capacitance			256		PF
Q_g	Total Gate Charge		$V_{DS}=50\text{V}, I_D=40\text{A},$ $V_{GS}=10\text{V}$		152	
Q_{gs}	Gate-Source Charge			32		nC
Q_{gd}	Gate-Drain Charge			61		nC
Switching Times						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=30\text{V}, I_D=40\text{A}, R_L=15\Omega$ $V_{GS}=10\text{V}, R_G=2.5\Omega$		35		nS
t_r	Turn-on Rise Time			52		nS
$t_{d(off)}$	Turn-Off Delay Time			76		nS
t_f	Turn-Off Fall Time			21		nS
Source-Drain Diode Characteristics						
I_{SD}	Source-drain Current(Body Diode)			110		A
I_{SDM}	Pulsed Source-Drain Current(Body Diode)			420		A
V_{SD}	Forward On Voltage _e (NOTE 1)	$T_J=25^{\circ}\text{C}, I_{SD}=40\text{A}, V_{GS}=0\text{V}$		0.87	0.99	V
t_{rr}	Reverse Recovery Time _e (NOTE 1)	$T_J=25^{\circ}\text{C}, I_F=75\text{A}$ $di/dt=100\text{A}/\mu\text{s}$		38		nS
Q_{rr}	Reverse Recovery Charge _e (NOTE 1)			69		nC
t_{on}	Forward Turn-on Time	Intrinsic turn-on time is negligible(turn-on is dominated by L_S+L_D)				

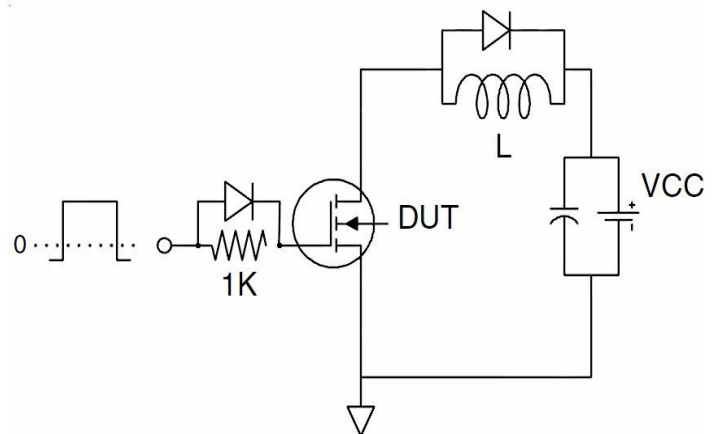
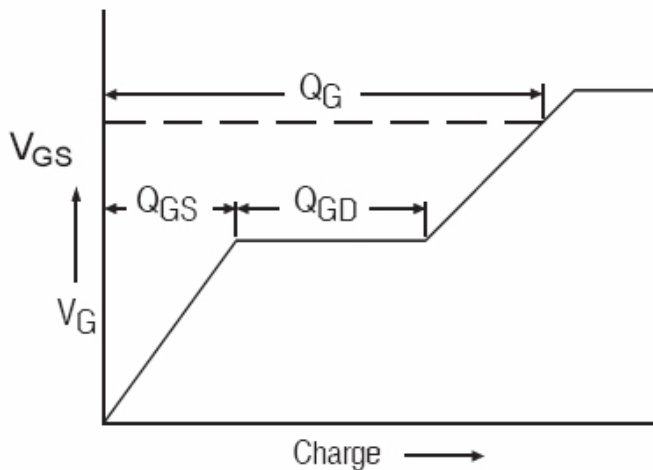
Notes 1. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 1.5\%$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$

Test Circuit

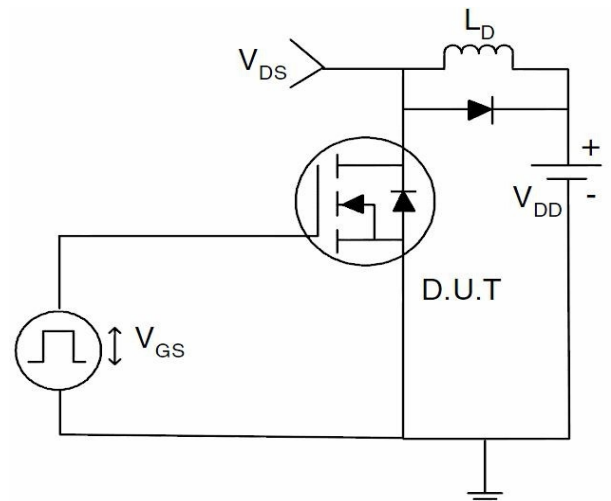
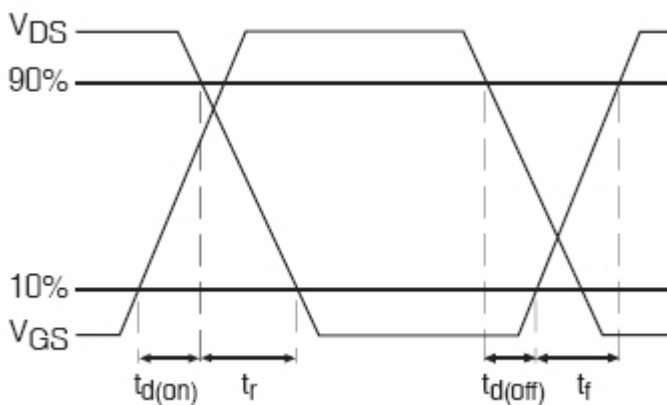
1) EAS Test Circuits



2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:





TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS (Curves)

Figure1. Output Characteristics

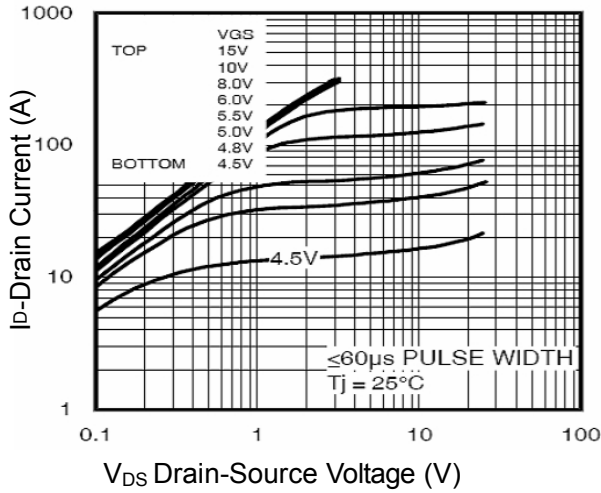


Figure2. Transfer Characteristics

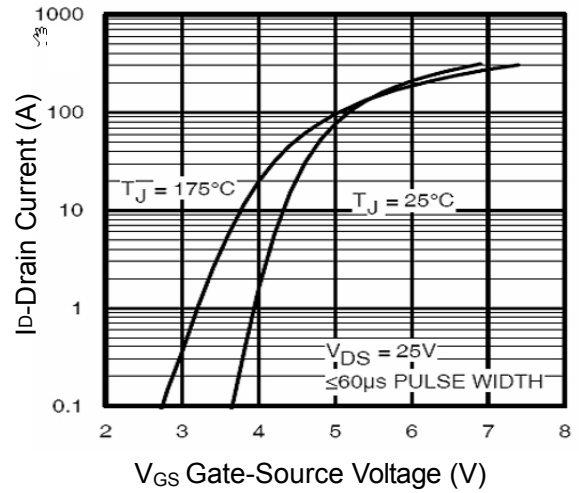


Figure3. ID vs Junction Temperature

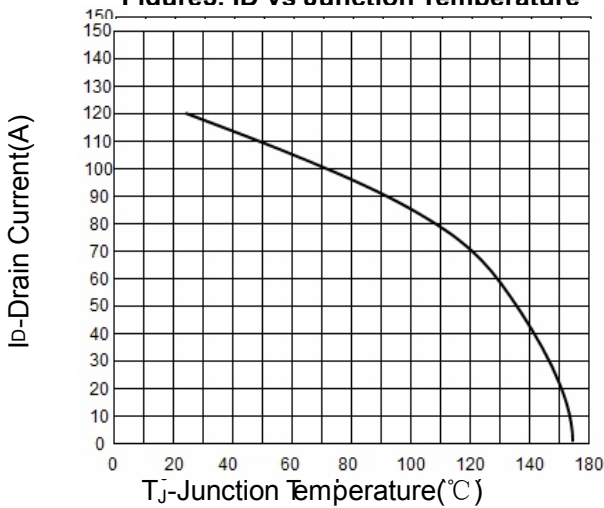


Figure4. Rds(on) Vs Junction Temperature

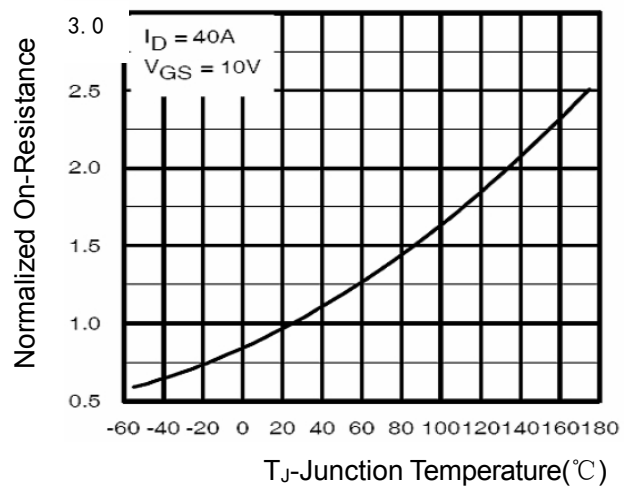


Figure5. BVDS vs Junction Temperature

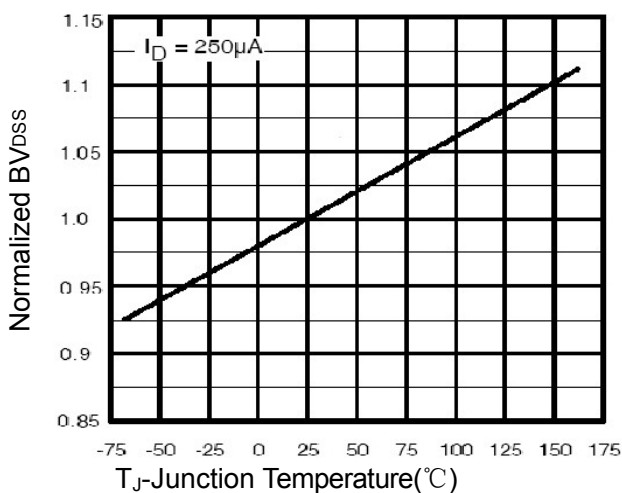
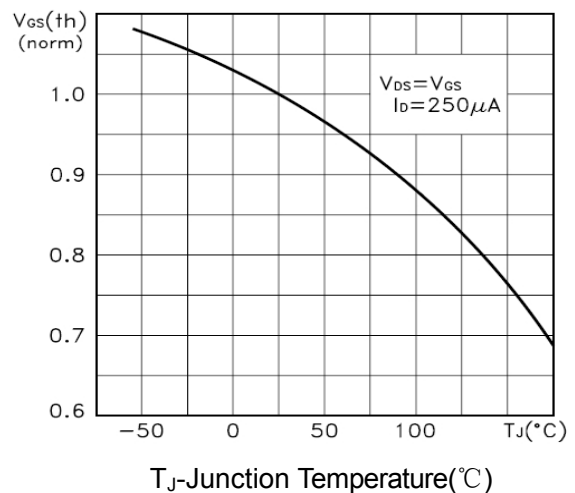
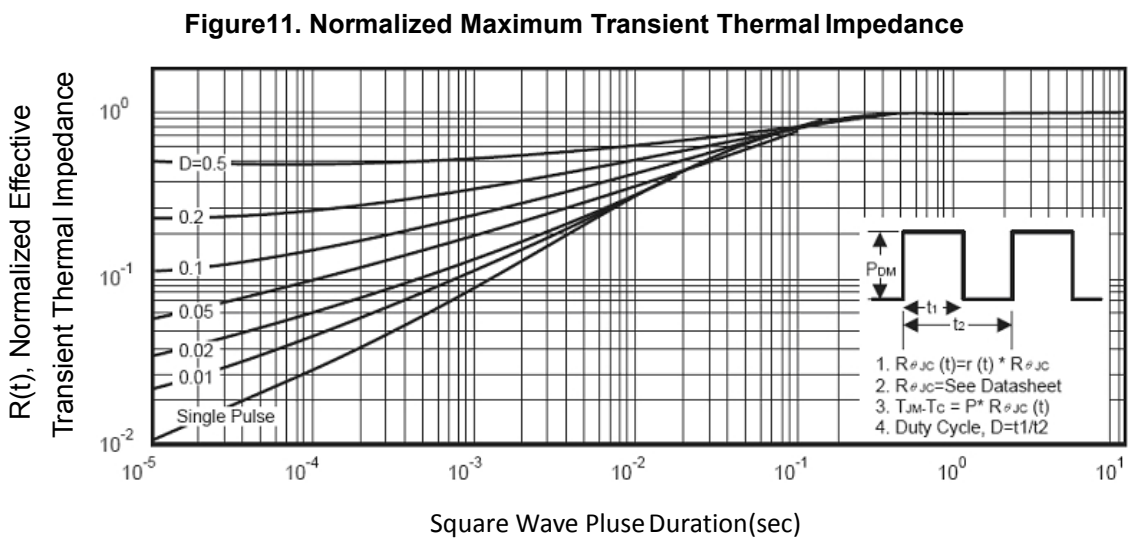
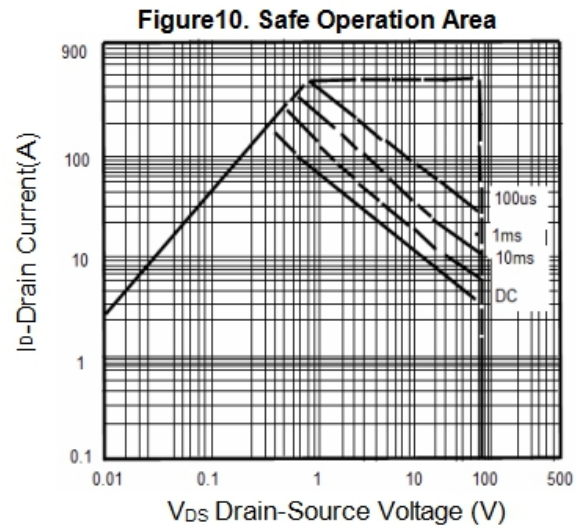
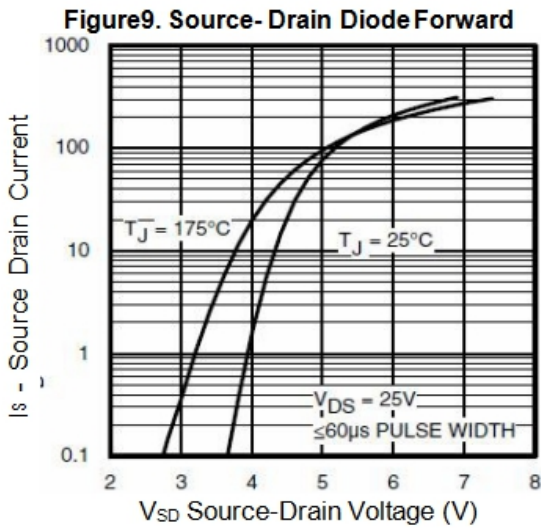
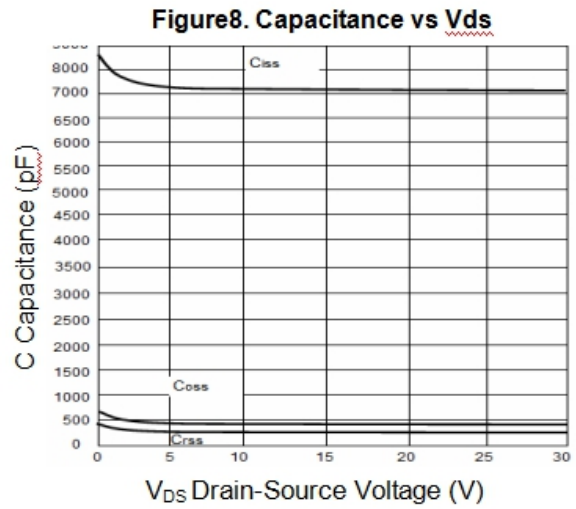
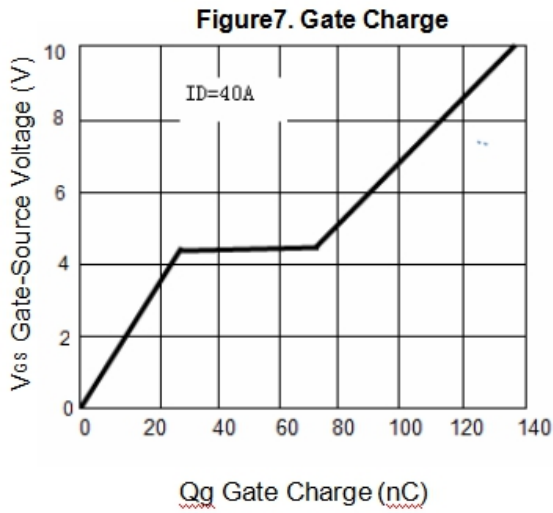


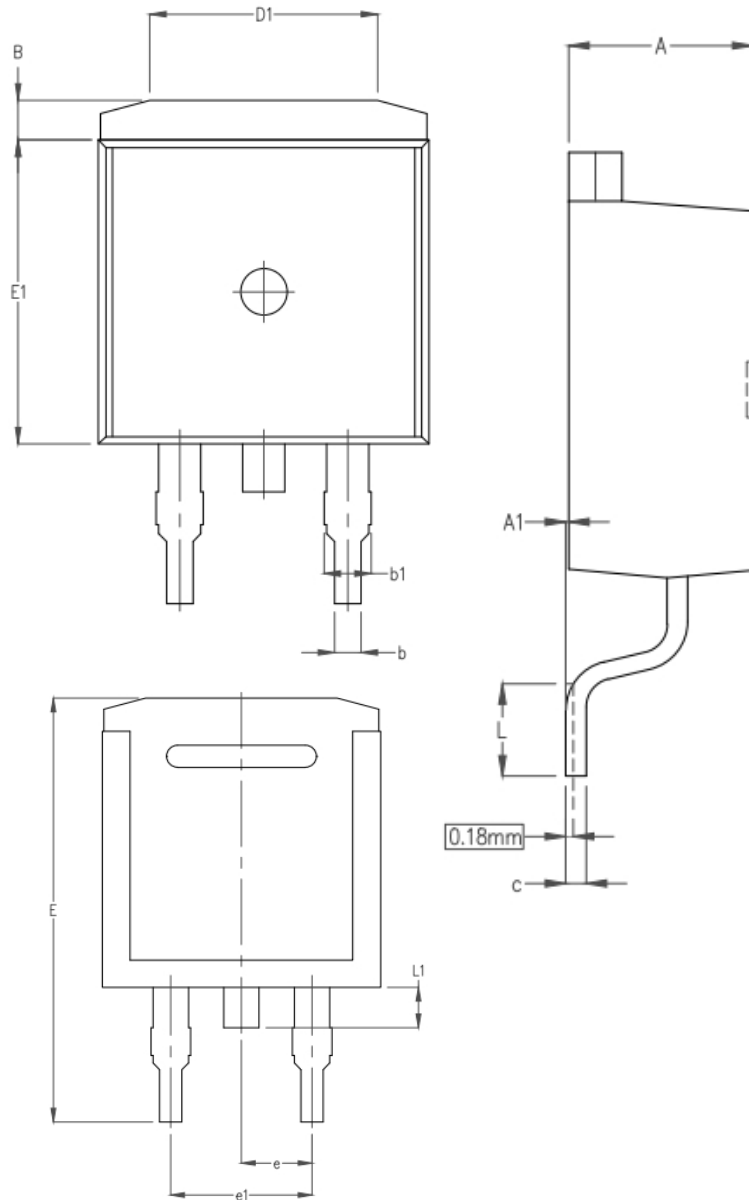
Figure6. VGS(th) vs Junction Temperature







TO-263 Package Information



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	4.45	4.50	4.55
A1	0	0.07	0.15
B	1.08	1.20	1.32
b	0.80TYP.		
b1	1.24	1.27	1.30
c	0.48	0.50	0.52
D	9.95	10.00	10.05
D1	6.89REF.		
E	15.09	15.24	15.39
E1	9.15	9.20	9.25
e	2.51	2.54	2.57
e1	5.05	5.08	5.11
L	2.29	2.54	2.79

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